

## SiC SCHOTTKY DIODE TYPE 6A

### Features

- Low reverse current
- Good surge current capability
- No reverse recovery current
- Halogen Free, and RoHS Compliant
- System efficiency improvement over Si diodes
- Suitable for high power application
- $V_{DC}$  650 V
- $I_F$  ( $T_C=25 / 147\text{ }^\circ\text{C}$ ) 14A/6A

### Benefits

- Higher system level efficiency
- Increase system power density
- Reduction of heat sink requirements
- Parallel devices without thermal runaway

### Applications

- Switch mode power supplies (SMPS)
- Server/telecom power supplies
- Industrial power supplies
- Solar
- UPS

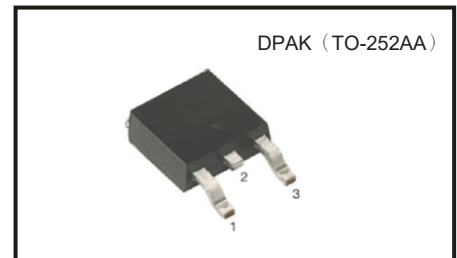
### Maximum Ratings

Operating Junction Temperature :  $-55\text{ }^\circ\text{C}$  to  $+175\text{ }^\circ\text{C}$

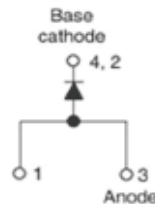
Storage Temperature :  $-55\text{ }^\circ\text{C}$  to  $+150\text{ }^\circ\text{C}$

Part Number	Maximum Recurrent Peak Reverse Voltage	Maximum DC Blocking Voltage
CSR006-065D3	650V	650V

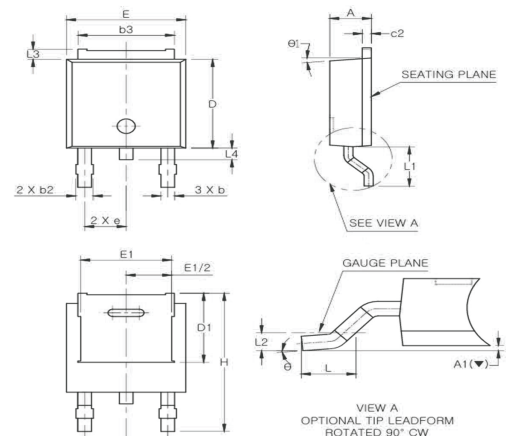
Maximum Rating	Symbol	Conditions	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	$T_J=25\text{ }^\circ\text{C}$	650	V
Continuous forward current	$I_F$	$T_C=25\text{ }^\circ\text{C}$	14	A
		$T_C=147\text{ }^\circ\text{C}$	6	
Non-repetitive forward surge current	$I_{FSM}$	$T_C=25\text{ }^\circ\text{C}$ , $t_p=10\mu\text{s}$	45	A
Non-repetitive forward surge current	$I_{F\text{ max.}}$	$T_C=25\text{ }^\circ\text{C}$ , $t_p=10\mu\text{s}$	450	
Power Dissipation	$P_D$	$T_C=25\text{ }^\circ\text{C}$	65	W



DPAK (TO-252AA)



Package Dimensions



SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.40
A1 (▽)	0.00	—	0.127
b	0.66	0.76	0.86
b2	—	—	0.96
b3	5.04	5.34	5.64
c2	0.40	0.50	0.60
D	5.90	6.10	6.30
D1	(4.75)		
E	6.40	6.60	6.80
E1	(5.04)		
e	2.30 BSC		
H	9.20	9.50	9.80
L	1.27	1.47	1.67
L1	2.50	2.70	2.90
L2	0.508 BSC		
L3	0.50	0.70	0.90
L4	0.60	0.80	1.00
θ	0°	—	10°
θ1	(5°)		

#### NOTE

1. THESE DIMENSIONS DO NOT INCLUDE PROTRUSIONS OF THE MOLD.
2. THE "( )" MARK IS THE REFERENCE
3. COPLANARITY : MAX 0.10mm
4. THE "L4" SYMBOL IS A PROTRUSION OF THE LEAD FRAME.

**Electrical Characteristics**, at  $T_J = 25^\circ\text{C}$ , unless otherwise specified.

Static Characteristics	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
DC blocking voltage	$V_{DC}$		650	-	-	V
Diode forward voltage	$V_F$	$I_F = 6\text{A}$ , $T_J = 25^\circ\text{C}$	-	1.3	1.5	
		$I_F = 6\text{A}$ , $T_J = 175^\circ\text{C}$	-	1.6	-	
Reverse current	$I_R$	$V_R = 650\text{V}$ , $T_J = 25^\circ\text{C}$	-	1	50	$\mu\text{A}$
		$V_R = 650\text{V}$ , $T_J = 175^\circ\text{C}$	-	5	200	

### AC Characteristics

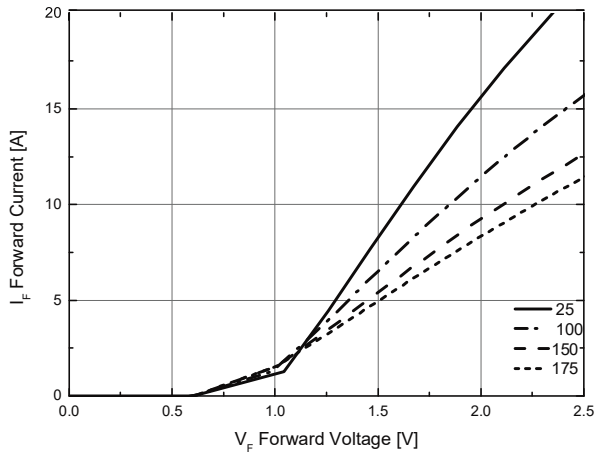
Static Characteristics	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Total capacitive charge	$Q_C$	$V_R = 400\text{V}$	-	12	-	nC
Total capacitance	C	$V_R = 0\text{V}$ , $f = 1\text{ MHz}$	-	340	-	pF
		$V_R = 400\text{V}$ , $f = 1\text{ MHz}$	-	32	-	
Total capacitive energy	$E_C$	$V_R = 400\text{V}$	-	5	-	$\mu\text{J}$

### Thermal Characteristics

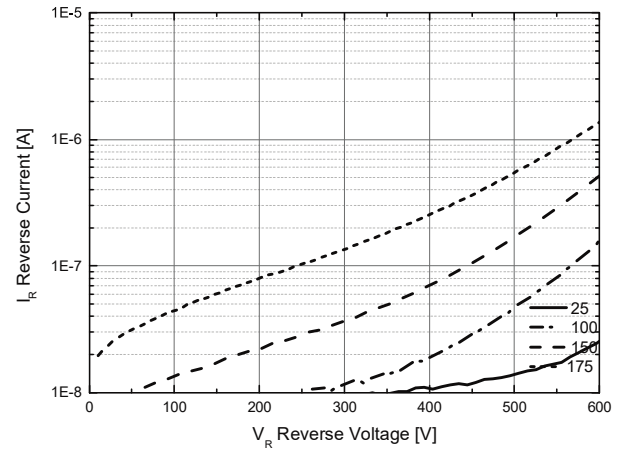
Static Characteristics	Symbol	Values	Unit
		max.	
Thermal resistance from junction to case	$R_{\theta JC}$	2.3	$^\circ\text{C/W}$

## Typical Device Performance

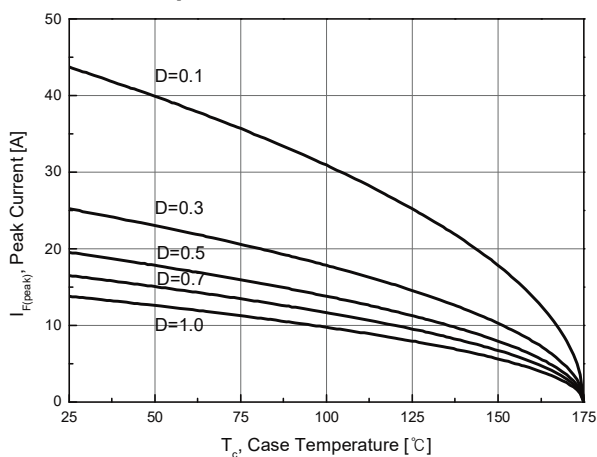
**Fig.1 Typical Forward Characteristics**  
( $I_F = f(V_F)$ ,  $t_p = 20\mu s$ )



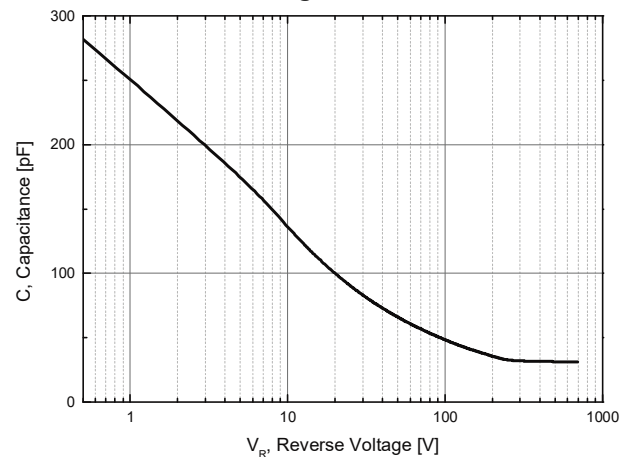
**Fig.2 Typical Reverse Current as Function of Reverse Voltage**



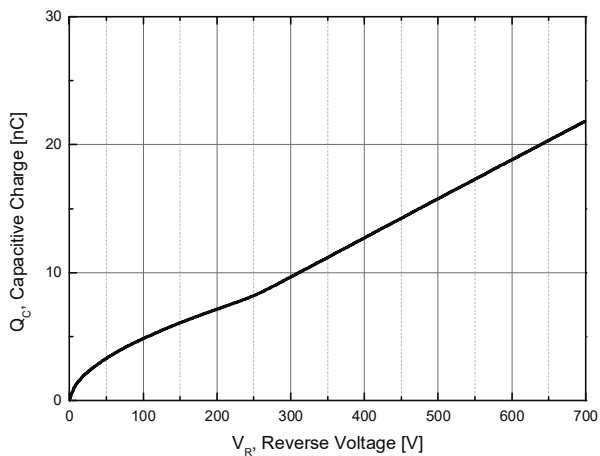
**Fig.3 Diode Forward Current as Function of Temperature**



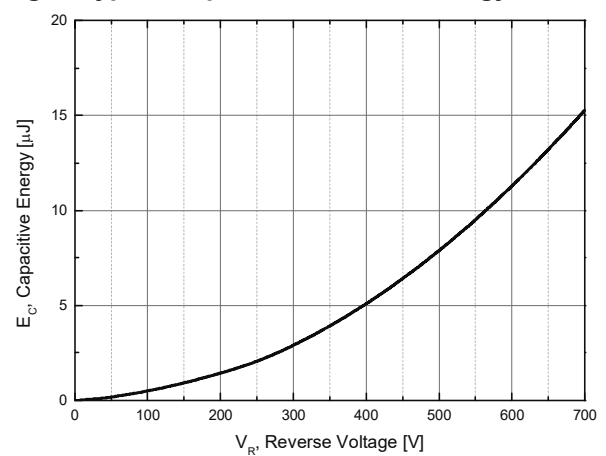
**Fig.4 Typical Capacitance as Function of Reverse Voltage**



**Fig.5 Typical capacitive charge**

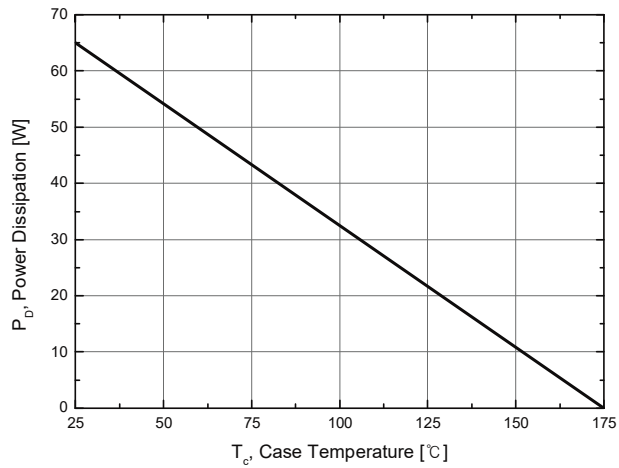


**Fig.6 Typical capacitance stored energy**

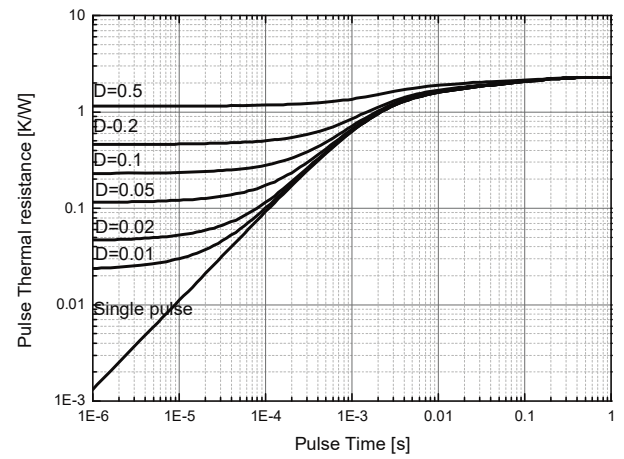


## Typical Device Performance

**Fig.7 Power Dissipation as Function of Case Temperature**



**Fig.8 Transient Thermal impedance**



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